# **HEF4082B**

# **Dual 4-input AND gate**

Rev. 5 — 16 November 2011

Product data sheet

## 1. General description

The HEF4082B is a dual 4-input AND gate. The outputs are fully buffered for highest noise immunity and pattern insensitivity to output impedance variations.

It operates over a recommended  $V_{DD}$  power supply range of 3 V to 15 V referenced to  $V_{SS}$  (usually ground). Unused inputs must be connected to  $V_{DD}$ ,  $V_{SS}$ , or another input.

### 2. Features and benefits

- Fully static operation
- 5 V, 10 V, and 15 V parametric ratings
- Standardized symmetrical output characteristics
- Inputs and outputs are protected against electrostatic effects
- Specified from -40 °C to +85 °C and -40 °C to +125 °C
- Complies with JEDEC standard JESD 13-B

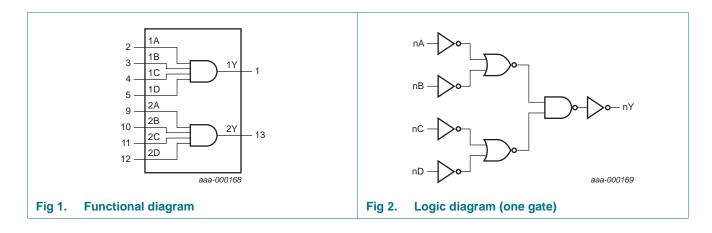
### 3. Ordering information

Table 1. Ordering information

All types operate from  $-40~^{\circ}\text{C}$  to  $+125~^{\circ}\text{C}$ .

Type number	Package								
	Name	Description	Version						
HEF4082BP	DIP14	plastic dual in-line package; 14 leads (300 mil)	SOT27-1						
HEF4082BT	SO14	plastic small outline package; 14 leads; body width 3.9 mm	SOT108-1						

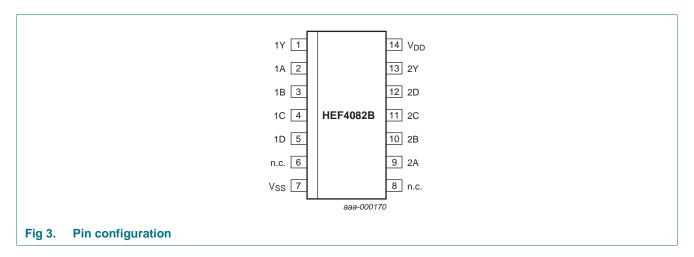
## 4. Functional diagram





# 5. Pinning information

### 5.1 Pinning



### 5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
1A, 1B, 1C, 1D	2, 3, 4, 5	input
2A, 2B, 2C, 2D	9, 10, 11, 12	input
1Y, 2Y	1, 13	output
n.c.	6, 8	not connected
V <sub>SS</sub>	7	ground (0 V)
$V_{DD}$	14	supply voltage

# 6. Functional description

Table 3. Function table [1]

Input	put							
nA	nB	nC	nD	nY				
L	X	X	X	L				
X	L	Χ	X	L				
X	Χ	L	X	L				
X	Χ	Χ	L	L				
Н	Н	Н	Н	Н				

<sup>[1]</sup> H = HIGH voltage level; L = LOW voltage level; X = don't care.

## 7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to V<sub>SS</sub> = 0 V (ground).

					•
Symbol	Parameter	Conditions	Min	Max	Unit
$V_{DD}$	supply voltage		-0.5	+18	V
I <sub>IK</sub>	input clamping current	$V_I < -0.5 \text{ V or } V_I > V_{DD} + 0.5 \text{ V}$	-	±10	mA
VI	input voltage		-0.5	$V_{DD} + 0.5$	V
l <sub>OK</sub>	output clamping current	$V_O < -0.5 \text{ V or } V_O > V_{DD} + 0.5 \text{ V}$	-	±10	mA
I <sub>I/O</sub>	input/output current		-	±10	mA
I <sub>DD</sub>	supply current		-	50	mA
T <sub>stg</sub>	storage temperature		-65	+150	°C
T <sub>amb</sub>	ambient temperature		-40	+125	°C
P <sub>tot</sub>	total power dissipation	$T_{amb} = -40  ^{\circ}\text{C} \text{ to + } 125  ^{\circ}\text{C}$			
		DIP14	<u>[1]</u> -	750	mW
		SO14	[2] _	500	mW
Р	power dissipation	per output	-	100	mW

<sup>[1]</sup> For DIP14 packages: above  $T_{amb}$  = 70 °C,  $P_{tot}$  derates linearly with 12 mW/K.

### 8. Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{DD}$	supply voltage		3	15	V
$V_{I}$	input voltage		0	$V_{DD}$	V
T <sub>amb</sub>	ambient temperature	in free air	-40	+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{DD} = 5 V$	-	3.75	ns/V
		V <sub>DD</sub> = 10 V	-	0.5	ns/V
		V <sub>DD</sub> = 15 V	-	0.08	ns/V

#### 9. Static characteristics

Table 6. Static characteristics

 $V_{SS} = 0$  V;  $V_I = V_{SS}$  or  $V_{DD}$ ; unless otherwise specified.

Symbol	Parameter	Conditions	$V_{DD}$	T <sub>amb</sub> =	T <sub>amb</sub> = -40 °C		T <sub>amb</sub> = +25 °C		T <sub>amb</sub> = +85 °C		+125 °C	Unit
				Min	Max	Min	Max	Min	Max	Min	Max	
	HIGH-level	$ I_O  < 1 \mu A$	5 V	3.5	-	3.5	-	3.5	-	3.5	-	V
	input voltage		10 V	7.0	-	7.0	-	7.0	-	7.0	-	V
			15 V	11.0	-	11.0	-	11.0	-	11.0	-	V
·-	LOW-level	$ I_O  < 1 \mu A$	5 V	-	1.5	-	1.5	-	1.5	-	1.5	V
	input voltage		10 V	-	3.0	-	3.0	-	3.0	-	3.0	V
			15 V	-	4.0	-	4.0	-	4.0	-	4.0	V

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<sup>[2]</sup> For SO14 packages: above  $T_{amb}$  = 70 °C,  $P_{tot}$  derates linearly with 8 mW/K.

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 Table 6.
 Static characteristics ...continued

 $V_{SS} = 0 \ V$ ;  $V_I = V_{SS}$  or  $V_{DD}$ ; unless otherwise specified.

Symbol	Parameter	Conditions	$V_{DD}$	T <sub>amb</sub> =	–40 °C	T <sub>amb</sub> =	+25 °C	T <sub>amb</sub> =	+85 °C	T <sub>amb</sub> =	+125 °C	Unit
				Min	Max	Min	Max	Min	Max	Min	Max	
$V_{OH}$	HIGH-level	$ I_{O}  < 1 \mu A$	5 V	4.95	-	4.95	-	4.95	-	4.95	· -	V
	output voltage		10 V	9.95	-	9.95	-	9.95	-	9.95	-	V
			15 V	14.95	-	14.95	-	14.95	-	14.95	-	V
$V_{OL}$	LOW-level	$ I_O  < 1 \mu A$	5 V	-	0.05	-	0.05	-	0.05	-	0.05	V
	output voltage		10 V	-	0.05	-	0.05	-	0.05	-	0.05	V
			15 V	-	0.05	-	0.05	-	0.05	-	0.05	V
I <sub>OH</sub>	HIGH-level output current	$V_0 = 2.5 \text{ V}$	5 V	-	-1.7	-	-1.4	-	-1.1	-	-1.1	mΑ
		$V_0 = 4.6 \text{ V}$	5 V	-	-0.64	-	-0.5	-	-0.36	-	-0.36	mΑ
		V <sub>O</sub> = 9.5 V	10 V	-	-1.6	-	-1.3	-	-0.9	-	-0.9	mΑ
		V <sub>O</sub> = 13.5 V	15 V	-	-4.2	-	-3.4	-	-2.4	-	-2.4	mΑ
I <sub>OL</sub>	LOW-level	$V_0 = 0.4 \ V$	5 V	0.64	-	0.5	-	0.36	-	0.36	-	mΑ
	output current	V <sub>O</sub> = 0.5 V	10 V	1.6	-	1.3	-	0.9	-	0.9	-	mΑ
		V <sub>O</sub> = 1.5 V	15 V	4.2	-	3.4	-	2.4	-	2.4	-	mΑ
I <sub>I</sub>	input leakage current		15 V	-	±0.1	-	±0.1	-	±1.0	-	±1.0	μА
I <sub>DD</sub>	supply current	all valid input	5 V	-	0.25	-	0.25	-	7.5	-	7.5	μΑ
		combinations;	10 V	-	0.5	-	0.5	-	15.0	-	15.0	μΑ
		$I_O = 0 A$	15 V	-	1.0	-	1.0	-	30.0	-	30.0	μΑ
Cı	input capacitance			-	-	-	7.5	-	-	-	-	pF

## 10. Dynamic characteristics

Table 7. Dynamic characteristics

 $T_{amb} = 25$  °C;  $C_L = 50$  pF;  $t_r = t_f \le 20$  ns; waveforms see Figure 4; test circuit see Figure 5; unless otherwise specified.

arrio		,					•	
Symbol	Parameter	Conditions	$V_{DD}$	Extrapolation formula	Min	Тур	Max	Unit
t <sub>pd</sub>	propagation delay	nA, nB, nC, nD to nY	5 V	[2] $38 + 0.55 \times C_L$	-	65	125	ns
			10 V	19 + 0.23 × C <sub>L</sub>	-	30	60	ns
			15 V	17 + 0.16 × C <sub>L</sub>	-	25	45	ns
	HIGH to LOW output	nY	5 V	$10 + 1.0 \times C_L$	-	60	120	ns
	transition time		10 V	$9 + 0.42 \times C_L$	-	30	60	ns
			15 V	$6 + 0.28 \times C_L$	-	20	40	ns
t <sub>TLH</sub>	LOW to HIGH output	nY	5 V	$10 + 1.0 \times C_L$	-	60	120	ns
	transition time		10 V	$9 + 0.42 \times C_L$	-	30	60	ns
		1	15 V	$6 + 0.28 \times C_L$	-	20	40	ns

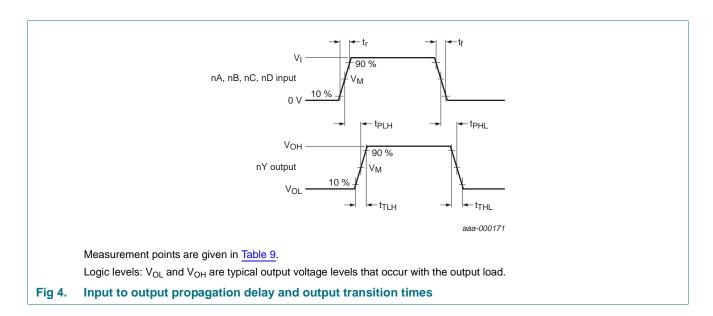
<sup>[1]</sup> The typical value of the propagation delay and output transition time can be calculated with the extrapolation formula (C<sub>L</sub> in pF).

Table 8. Dynamic power dissipation

 $V_{SS} = 0 \text{ V; } t_r = t_f \le 20 \text{ ns; } T_{amb} = 25 \text{ °C.}$ 

Symbol	Parameter	$V_{DD}$	Typical formula	where:
$P_D$	dynamic power dissipation	5 V	$P_D = 1500 \times f_i + \Sigma (f_o \times C_L) \times V_{DD}^2 (\mu W)$	$f_i$ = input frequency in MHz;
		10 V	$P_D = 6700 \times f_i + \Sigma (f_o \times C_L) \times V_{DD}^2 (\mu W)$	fo = output frequency in MHz;
		15 V	$P_D = 16800 \times f_i + \Sigma (f_0 \times C_L) \times V_{DD}^2 (\mu W)$	$C_L$ = output load capacitance in pF;
				$\Sigma(f_0 \times C_L)$ = sum of the outputs;
				V <sub>DD</sub> = supply voltage in V.

### 11. Waveforms



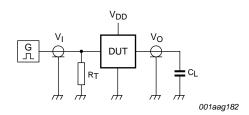
<sup>[2]</sup>  $t_{pd}$  is the same as  $t_{PHL}$  and  $t_{PLH}$ .

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Table 9. Measurement points

Supply voltage	Input	Output
$V_{DD}$	V <sub>M</sub>	V <sub>M</sub>
5 V to 15 V	0.5V <sub>DD</sub>	0.5V <sub>DD</sub>



Test data is given in Table 10.

Definitions for test circuit:

DUT = Device Under Test.

 $C_L$  = load capacitance including jig and probe capacitance.

 $R_T$  = termination resistance should be equal to the output impedance  $Z_0$  of the pulse generator.

Fig 5. Test circuit

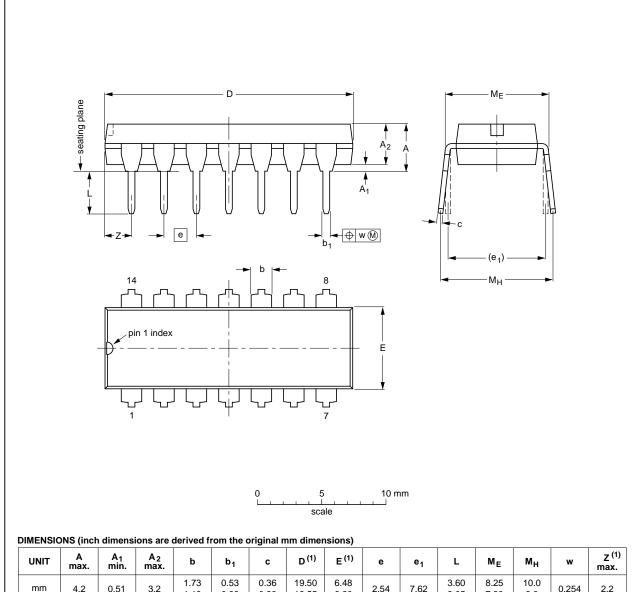
Table 10. Test data

Supply voltage	Input	Load	
$V_{DD}$	VI	t <sub>r</sub> , t <sub>f</sub>	C <sub>L</sub>
5 V to 15 V	V <sub>SS</sub> or V <sub>DD</sub>	≤ 20 ns	50 pF

# 12. Package outline

#### DIP14: plastic dual in-line package; 14 leads (300 mil)

SOT27-1



UNIT	A max.	A <sub>1</sub> min.	A <sub>2</sub> max.	b	b <sub>1</sub>	С	D <sup>(1)</sup>	E <sup>(1)</sup>	е	e <sub>1</sub>	L	ME	Мн	w	Z <sup>(1)</sup> max.
mm	4.2	0.51	3.2	1.73 1.13	0.53 0.38	0.36 0.23	19.50 18.55	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.2
inches	0.17	0.02	0.13	0.068 0.044	0.021 0.015	0.014 0.009	0.77 0.73	0.26 0.24	0.1	0.3	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.087

#### Note

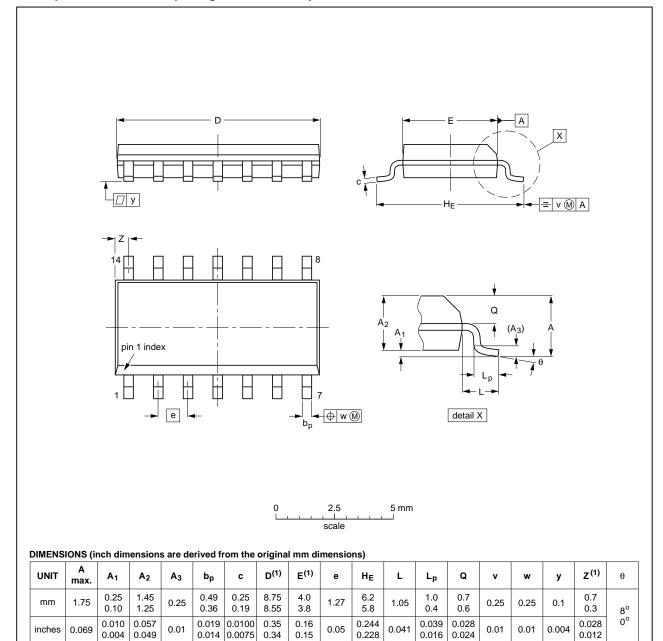
1. Plastic or metal protrusions of 0.25 mm (0.01 inch) maximum per side are not included.

OUTLINE	REFERENCES				EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOT27-1	050G04	MO-001	SC-501-14			<del>99-12-27</del> 03-02-13

Package outline SOT27-1 (DIP14) Fig 6.

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1



#### Note

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

OUTLINE	REFERENCES				EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOT108-1	076E06	MS-012				<del>99-12-27</del> 03-02-19

Fig 7. Package outline SOT108-1 (SO14)

## 13. Abbreviations

#### Table 11. Abbreviations

Acronym	Description
DUT	Device Under Test
ESD	ElectroStatic Discharge

# 14. Revision history

#### Table 12. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
HEF4082B v.5	20111116	Product data sheet	-	HEF4082B v.4
Modifications:	<ul><li>Legal pages</li><li>Changes in</li></ul>	s updated. "General description" and "	Features and benefits".	
HEF4082B v.4	20110823	Product data sheet	-	HEF4082B_CNV v.3
HEF4082B_CNV v.3	19950101	Product specification	-	HEF4082B_CNV v.2
HEF4082B_CNV v.2	19950101	Product specification	-	-

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